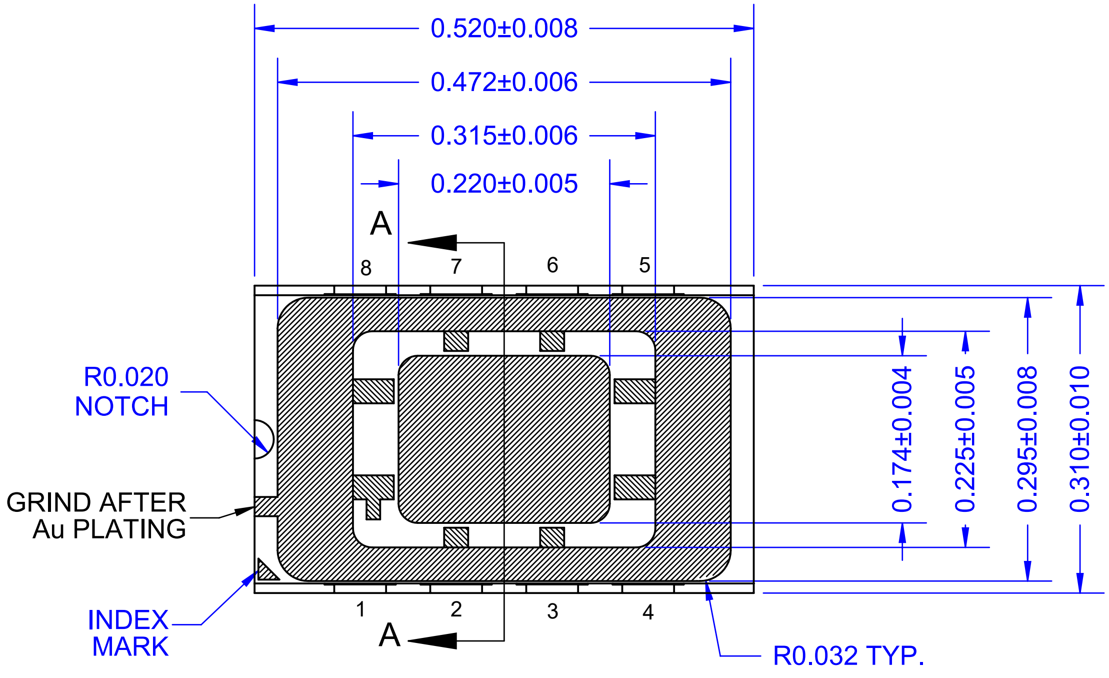
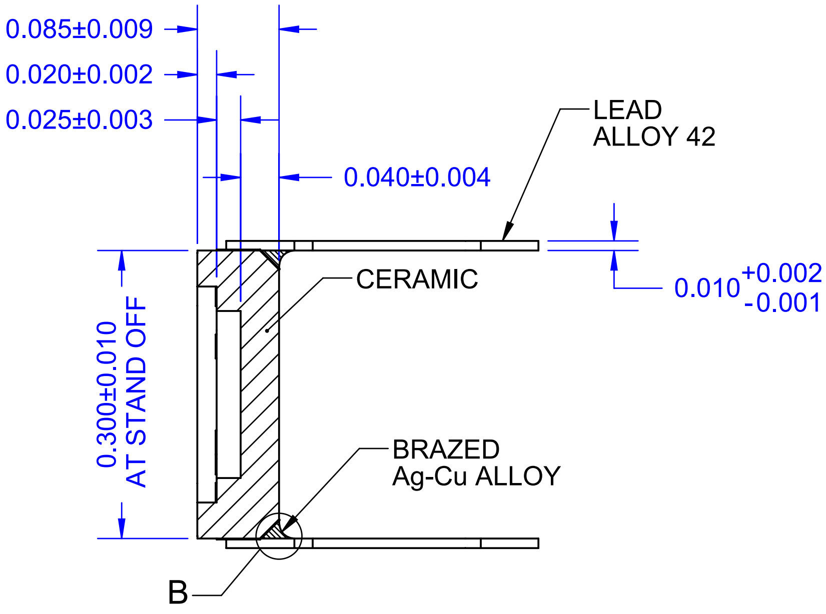
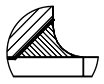
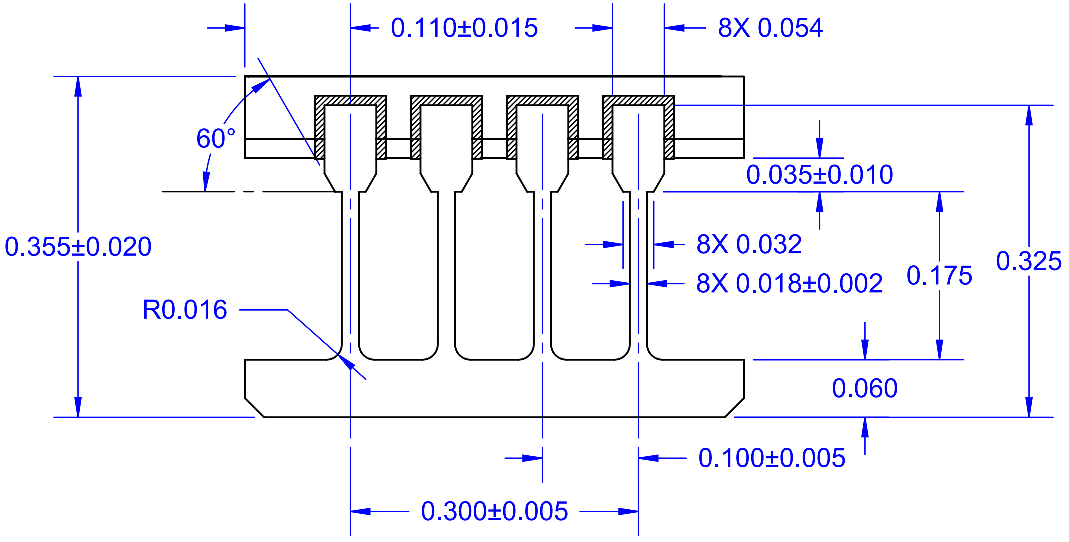


DIE PAD
0.170 x 0.220-inch
4.3 x 5.6mm





DETAIL B
SCALE 10 : 1



NOTES: (Unless Otherwise Specified).

1. GOLD PLATE 60 micro-inch over 100 micro-inch (MIN) NICKEL.
2. SEAL AREA TO BE METALLIZED.
3. SEE PART NUMBER TABLE FOR DIE ATTACH METALLIZATION.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE: 0.20 OHM MAX.
6. TOLERANCE ±0.005-INCH UNLESS OTHERWISE SPECIFIED.
7. CERAMIC (Al_2O_3 BLACK) SIDE-BRAZE PACKAGE KOVAR LEAD FRAME WITH GOLD METALLIZATION.

PART NUMBER TABLE

PART NUMBER	**DIE PAD**	**DWG**
CERDIP8F3-N170x220	GOLD	191225

APPROVALS		DATE
DRAWN	T.Au	06/30/16
ENG	M. Hart	06/30/16
MFG		
QA		
CUST		
REVISED		

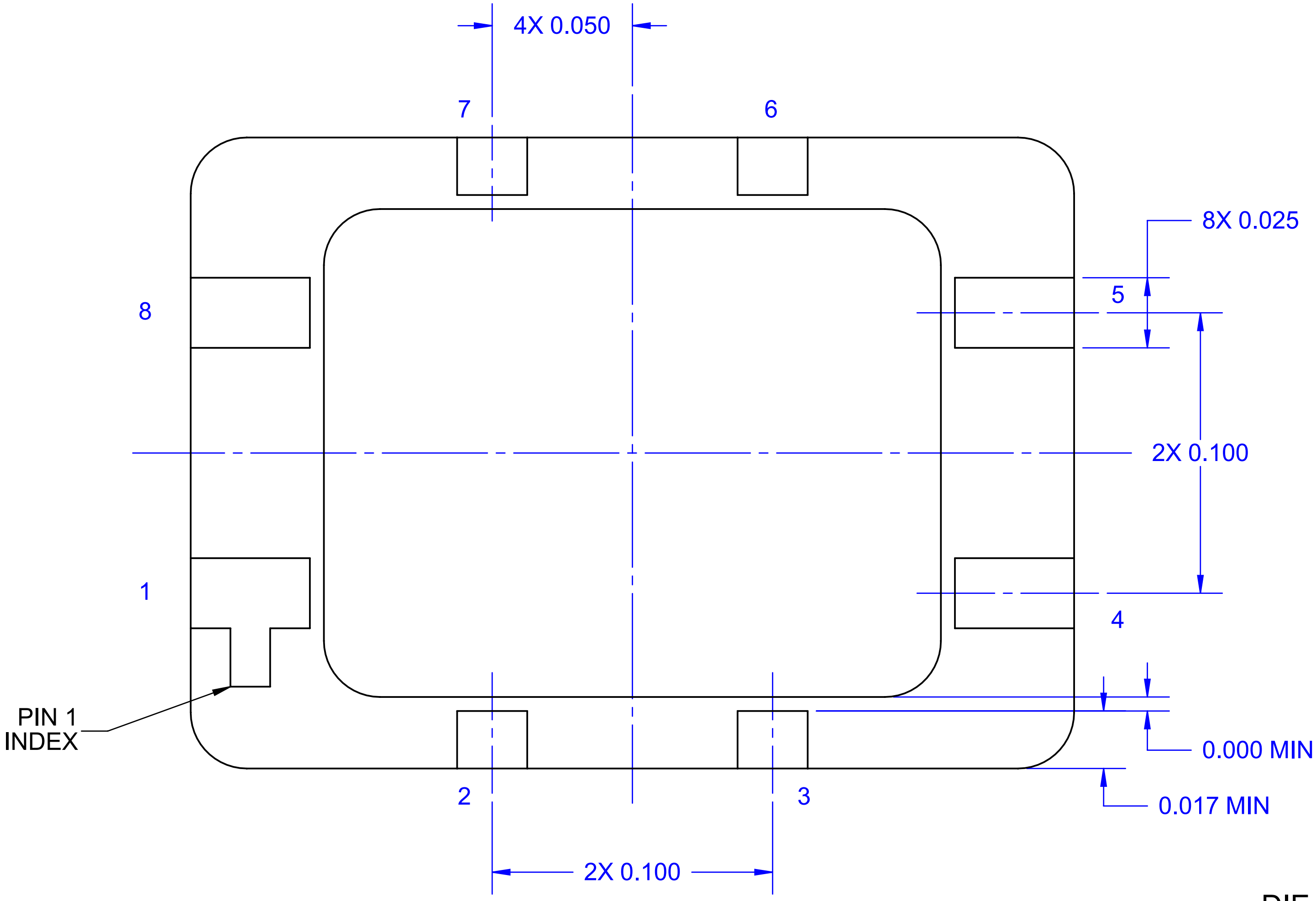
TopLine®

TITLE CERDIP8F3-N170x220
DIE PAD 4.3mm x 5.6mm

SCALE	SIZE	DRAWING NO.	REV
5:1	A	191225	A

DO NOT SCALE DRAWING
SHEET 1 OF 4

BONDING PADS



DIE PAD
0.170 x 0.220-inch
4.3 x 5.6mm

PART NUMBER TABLE		
PART NUMBER	**DIE PAD**	**DWG**
CERDIP8F3-N170x220	GOLD	191225

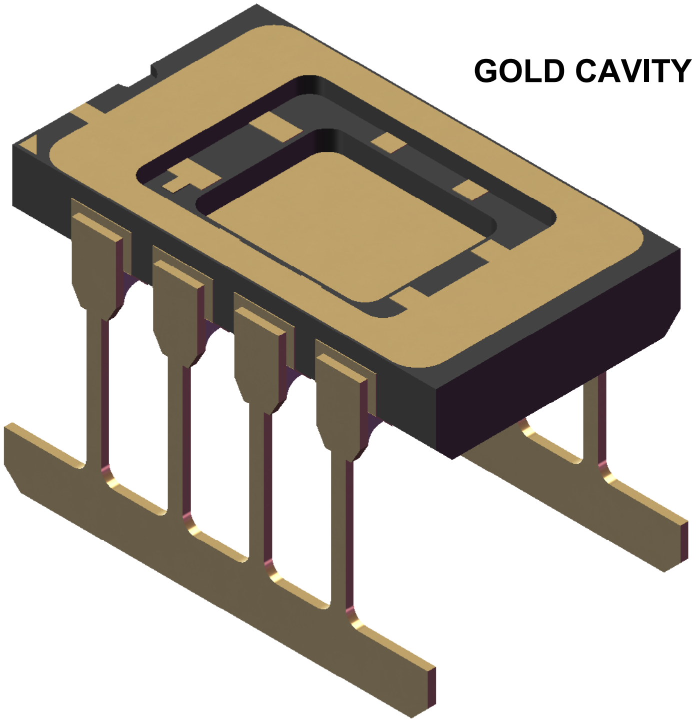
TopLine®

TITLE
CERDIP8F3-N170x220
DIE PAD 4.3mm x 5.6mm

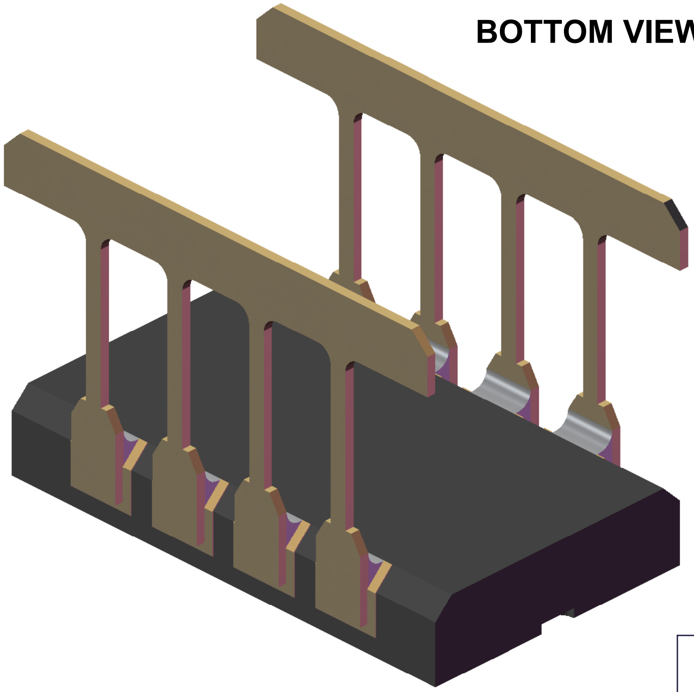
SCALE	SIZE	DRAWING NO.	REV
5:1	A	191225	A

DO NOT SCALE DRAWING

MODELS



GOLD CAVITY



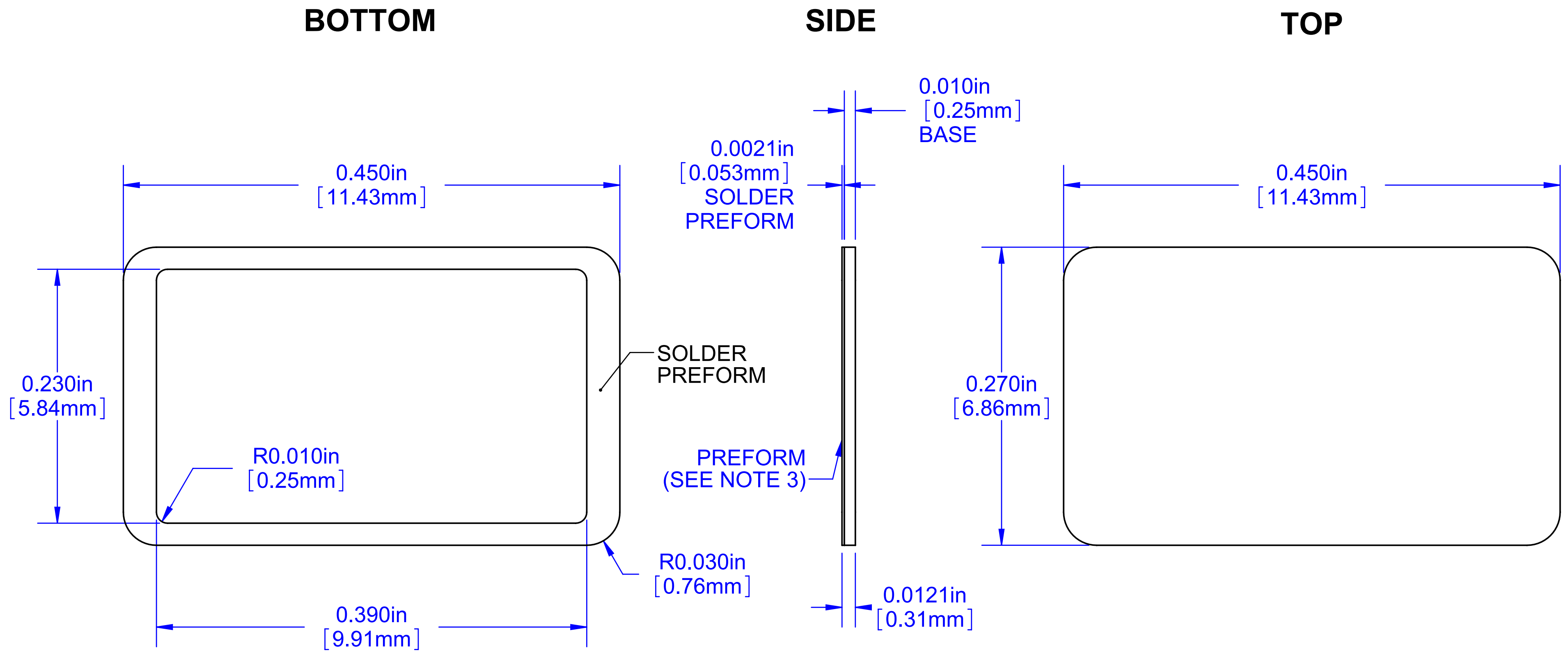
BOTTOM VIEW

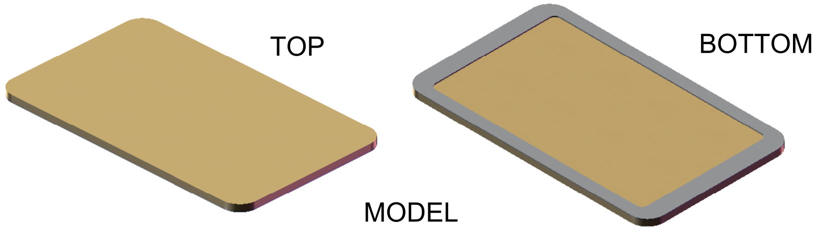
PART NUMBER TABLE		
PART NUMBER	**DIE PAD**	**DWG**
CERDIP8F3-N170x220	GOLD	191225

TopLine®

TITLE	CERDIP8F3-N170x220 DIE PAD 4.3mm x 5.6mm		
SCALE 6:1	SIZE A	DRAWING NO. 191225	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 4	

COMBO LID





NOTES:
1. BASE MATERIAL: KOVAR or ALLOY 42.

2. PLATING: Ni 50~350 MICRO-INCH PER SIDE.
Au 25 MICRO-INCH MIN PER SIDE.

3. SOLDER PREFORM: Au 80% ±1.0 Sn 20%.

4. FLATNESS 1.0 MIL(25µm) MAXIMUM PER 0.5-inch (12.7mm).

TopLine®

TITLE	CL-270x450-A COMBO LID		
SCALE 7:1	SIZE A	DRAWING NO. 191225	REV A
DO NOT SCALE DRAWING		SHEET 4 OF 4	